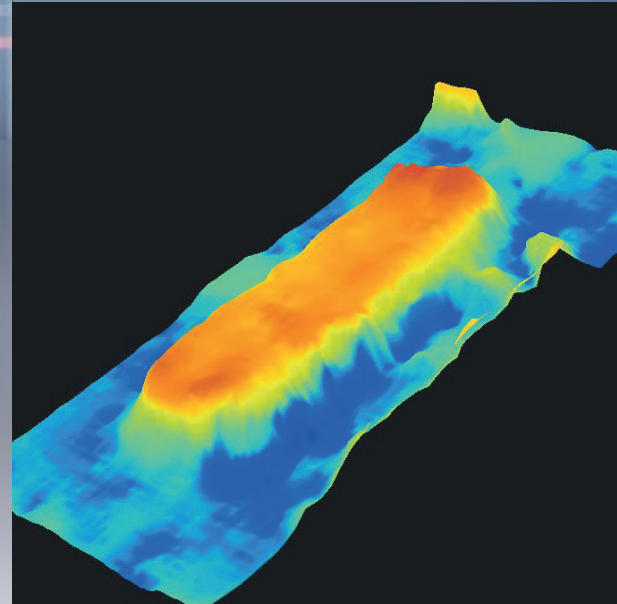




Solder Paste Inspection System (SPI) for In-Line Manufacturing



iS6052 SPI

Economical technology for reliable solder and
sinter paste inspection

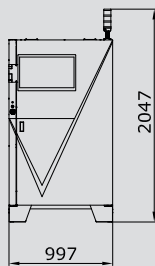
3D SPI



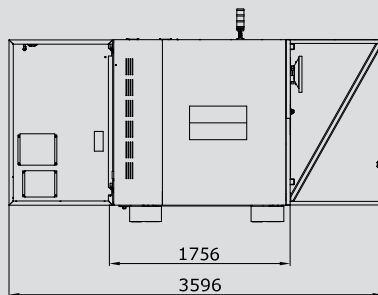
Technical Specifications

iS6052 SPI

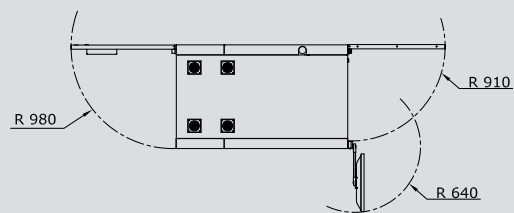
Front view



Side view



Top view



Dimensions in mm

iS6052 SPI		
Inspection Scope		Solder paste deposits (stencil printing or dispensing technology, up to pad sizes for 01005 components); sinter paste, adhesives, surface, height, print displacement, smearing, shape, coplanarity, open area analysis, OCR, DMC
		XMe-SPI
Camera technology	3D Sensor Technology	
	Z-resolution	0,1 µm
	Z-range	Up to 5mm
	Angled view cameras	
	Number of megapixel cameras	4
	Orthogonal camera	
	Resolution	12 µm
	Field of view	58 mm x 58 mm (2.2" x 2.2")
Inspection Speed		Up to 80 cm ² /s
Software	User interface	Viscom vVision
	Statistical process control	Viscom vSPC/SPC, open interface (optional)
	Verification station	Viscom vVerify
	Remote diagnosis	Viscom SRC (optional)
	Programming station	Viscom PST34 (optional)
System computer	Operating system	Windows®
	Processor	Intel®Core™i7
PCB handling	PCB dimensions	508 mm x 508 mm (20" x 20")
	PCB support	Optional
	Transport height	900 – 950 mm ± 20 mm (35.4" – 37.4" ± 0.7")
	Width adjustment	Automatic
	Transport concept	Single-track transport system, dual-lane option available
	PCB clamping	Pneumatic
	Upper transport clearance	50 mm (1.9")
Other system data	Lower transport clearance	50 mm (1.9"); 40 mm (1.5") with PCB support
	Positioning unit	Synchronous linear motor
	Interfaces	SMEMA, Hermes
	Power requirements	230/400 V, 50 Hz, 3P/N/PE +/- 10%; 4 – 6 bar working pressure
	System dimensions	997 mm x 1756 mm x 1753 mm (39.2" x 69.1" x 69") (W x D x H)
	Weight	Approx. 820 – 920 kg (1807.7 – 2028.2 lbs)

Specifications and other system information are subject to change without notice and may differ from the information displayed at the time of ordering.